

## Comparison of MX25L12845G/MX25L12873G and MX25L12835F/MX25L12873F

## 1. Introduction

This document compares the MX25L12835F/MX25L12873F (75nm "F" Version) and the MX25L12845G/ MX25L12873G (55nm "G" Version).

Generally, the F version and G version are pin and command compatible with the basic Read/Program/ Erase commands. There may be some differences if special features are used such as DTR mode, Advanced Sector Protection and Password protection.

The document does not provide detailed information on the individual devices, but highlights the major similarities and differences between them. The comparison covers the general features, performance, command codes and other differences.

The information provided in this document is based on datasheets listed in Section "10. Reference Documents". Newer versions of the datasheets may override the contents of this document. A comparison of key features is provided in "Table 1-1: Key Feature Comparison".



### Table 1-1: Key Feature Comparison

		Pa	art Number
	Feature	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
Process Techno	blogy	75nm	55nm
VCC		2.7V – 3.6V	2.7V - 3.6V
I/O		x1/x2/x4	x1/x2/x4
Sector Size	4KB	V	V
	32KB	V	V
	64KB	V	V
Program Buffer	Size	256Byte	256Byte
Security OTP		4KBit	4KBit
	Normal Read	50MHz	50MHz
Read Interface	Fast Read 1x I/O	104MHz	120MHz
Reau interiace	Fast Read 2x I/O	84MHz	80MHz
	Fast Read 4x I/O	84MHz	80MHz
Enhanced Freq	uency (x1/x2/x4: 10 dummy cycles)	133MHz	133MHz @ VCC=3.0V-3.6V
DTR (Maximum	i dummy cycle)	NA	100MHz @ VCC=3.0V-3.6V
Features			
QPI Interface		Yes	Yes
Read Enhance	Mode	Yes	Yes
Wrap around re	ad mode	Yes	Yes
Configurable du	immy cycle	Yes	Yes
Adjustable outp	ut driver	Yes	Yes
Suspend & Res	sume	Yes	Yes
Fast Boot (XIP)	Mode	Yes	Yes
Quad Enable (C	QE)=1 fixed	MX25L12873F	MX25L12873G
BP Protection		Yes	Yes
Password prote	ction	Yes	NA
volatile write pro	otection	Yes	Yes
Non-volatile Wr	ite Protection	Yes	Yes
SFDP		JESD216	JESD216B
Factory Mode		NA	Support on -08G



# 2. Package

MX25L12835F/MX25L12873F/MX25L12845G/MX25L12873G provide 8-SOP (200mil), 16-SOP (300mil) and 8-WSON (8x6mm)/(6x5mm) package options, and are pin out and physical dimensions identical. For more package information, please refer to the datasheets or contact our regional sales.

### Table 2-1: Package Pins Comparison

16-PIN SOP (300mil)							
MX25L12845G MX25L12873G	MX25L12835F MX25L12873F				,	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
DNU/SIO3	DNU/SIO3		1	16		SCLK	SCLK
VCC	VCC		2	15		SI/SIO0	SI/SIO0
RESET#	RESET#		3	14		NC	NC
NC	NC		4	13		NC	NC
NC	NC		5	12		NC	NC
NC	NC		6	11		NC	NC
CS#	CS#		7	10		GND	GND
SO/SIO1	SO/SIO1		8	9		WP#/SIO2	WP#/SIO2
		וו					

8-WSON (8x6mm) / (6x5mm)							
MX25L12845G MX25L12873G	MX25L12835F MX25L12873F					MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
CS#	CS#			8 🔳	[	VCC	VCC
SO/SIO1	SO/SIO1		2	7 🔳	[	RESET#/SIO3	RESET#/SIO3
WP#/SIO2	WP#/SIO2	■ 3	3	6 🔳		SCLK	SCLK
GND	GND		1	5 🗖	ſ	SI/SIO0	SI/SIO0
					ſ		

8-PIN SOP (200mil)							
MX25L12845G MX25L12873G	MX25L12835F MX25L12873F					MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
CS#	CS#		1	8		VCC	VCC
SO/SIO1	SO/SIO1		2	7		RESET#/SIO3	RESET#/SIO3
WP#/SIO2	WP#/SIO2		3	6		SCLK	SCLK
GND	GND		4	5		SI/SIO0	SI/SIO0



# 3. Command Set

The core commands for read, erase, and program are unchanged between the F and G versions. For a full list of commands and a description of their functions, please refer to each product's datasheet.

Command	Symbol	Description	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
	READ	Normal Read (1-1-1)	03h	03h
	FASTREAD	Fast Read (1-1-1)	0Bh	0Bh
	DREAD	Dual Output (1-1-2)	3Bh	3Bh
	2READ	2 I/O (1-2-2)	BBh	BBh
Read	QREAD	Quad Output (1-1-4)	6Bh	6Bh
	4READ	4 I/O (1-4-4)	EBh	EBh
	FASTDTRD	Fast DT Read	-	0Dh
	2DTRD	Dual I/O DT Read	-	BDh
	4DTRD	Quad I/O DT Read	-	EDh
	SE	Sector Erase (4KB)	20h	20h
Erase	BE32KB	Block Erase (32KB)	52h	52h
LIDSE	BE	Block Erase (64KB)	D8h	D8h
	CE	Chip Erase	60h or C7h	60h or C7h
Drogrom	PP	Page Program	02h	02h
Program	4PP	Quad Input Page Program	38h	38h
	RDID	Read ID	9Fh	9Fh
ID Read	RES	Read Electronic ID	ABh	ABh
	REMS	Read Electronic & Manufacturer ID	90h	90h
	QPIID	QPI ID Read	AFh	AFh

Table 3-1: Command Set Comparison (Read/Erase/Program/ID Read)



Command	Symbol	Description	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
	RDSR	Read Status Register	05h	05h
	WRSR	Write Status Register	01h	01h
	RDSCUR	Read Security Register	2Bh	2Bh
Register	WRSCUR	Write Security Register	2Fh	2Fh
	RDFBR	Read Fast Boot Register	16h	16h
	WRFBR	Write Fast Boot Register	17h	17h
	ESFBR	Erase Fast Boot Register	18h	18h
	WREN	Write Enable	06h	06h
	WRDI	Write Disable	04h	04h
	EQIO	Enable QPI	35h	35h
	RSTQIO	Disable QPI	F5h	F5h
Mode	SBL	Set Burst Length	C0h	C0h
	PGM/ERS Suspend	Suspends Program/Erase	B0h	B0h
	PGM/ERS Resume	Resumes Program/Erase	30h	30h
	FMEN	Factory Mode Enable	-	41h (with -08G only)
	NOP	No Operation	00h	00h
Reset	RSTEN	Reset Enable	66h	66h
	RST	Reset Memory	99h	99h

## Table 3-1: Command Set Comparison (Register/Mode/Reset)



Command	Symbol	Description	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
	WRLR	Write Lock Register	2Ch	2Ch
	RDLR	Read Lock Register	2Dh	2Dh
	WRPASS	Write Password Register	28h	-
	RDPASS	Read Password Register	27h	-
	PASSULK	Password Unlock	29h	-
	WRSPB	SPB Bit Program	E3h	E3h
Security	ESSPB	All SPB Bit Erase	E4h	E4h
occurry	RDSPB	Read SPB Status	E2h	E2h
	SPBLK	SPB Lock Set	A6h	-
	RDSPBLK	Read SPB Lock Register	A7h	A7h
	WRDPB	Write DPB Register	E1h	E1h
	RDDPB	Read DPB Register	E0h	E0h
	GBLK	Gang Block Lock	7Eh	7Eh
	GBULK	Gang Block Unlock	98h	98h

## Table 3-1: Command Set Comparison (Security)



# 4. Data Protection

Both F and G version products provide two write protection modes to easily protect sectors from inadvertent changes and will be discussed in more detail below.

## 4-1. BP bit Block Protection

All of the listed Macronix flash can use BP bits in the Status Register to select groups of memory areas for write protection. All the regions protected by G version can be protected by F version with the identical BP setting. Please refer to the following comparison table.

### Table 4-1: Block Protection (BP) Comparison of MX25L12835F/73F and MX25L12845G/73G

Status bit			:	Protect Level		
BP3	BP2	BP1	BP0	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G	
0	0	0	0	0 (none)	0 (none)	
0	0	0	1	1 (1 block, protected block 255 <sup>th</sup> )	1 (1 block, protected block 255 <sup>th</sup> )	
0	0	1	0	2 (2 blocks, block 254 <sup>th</sup> -255 <sup>th</sup> )	2 (2 blocks, block 254 <sup>th</sup> -255 <sup>th</sup> )	
0	0	1	1	3 (4 blocks, block 252 <sup>nd</sup> -255 <sup>th</sup> )	3 (4 blocks, block 252 <sup>nd</sup> -255 <sup>th</sup> )	
0	1	0	0	4 (8 blocks, block 248 <sup>th</sup> -255 <sup>th</sup> )	4 (8 blocks, block 248 <sup>th</sup> -255 <sup>th</sup> )	
0	1	0	1	5 (16 blocks, block 240 <sup>th</sup> -255 <sup>th</sup> )	5 (16 blocks, block 240 <sup>th</sup> -255 <sup>th</sup> )	
0	1	1	0	6 (32 blocks, block 224 <sup>th</sup> -255 <sup>th</sup> )	6 (32 blocks, block 224 <sup>th</sup> -255 <sup>th</sup> )	
0	1	1	1	7 (64 blocks, block 192 <sup>nd</sup> -255 <sup>th</sup> )	7 (64 blocks, block 192 <sup>nd</sup> -255 <sup>th</sup> )	
1	0	0	0	8 (128 blocks, block 128 <sup>th</sup> -255 <sup>th</sup> )	8 (128 blocks, block 128 <sup>th</sup> -255 <sup>th</sup> )	
1	0	0	1	9 (256 blocks, protected all)	9 (256 blocks, protected all)	
1	0	1	0	10 (256 blocks, protected all)	10 (256 blocks, protected all)	
1	0	1	1	11 (256 blocks, protected all)	11 (256 blocks, protected all)	
1	1	0	0	12 (256 blocks, protected all)	12 (256 blocks, protected all)	
1	1	0	1	13 (256 blocks, protected all)	13 (256 blocks, protected all)	
1	1	1	0	14 (256 blocks, protected all)	14 (256 blocks, protected all)	
1	1	1	1	15 (256 blocks, protected all)	15 (256 blocks, protected all)	

#### Protected Area Sizes (T/B bit = 0)



## 4-2. Individual Sector Protection Mode

The second mode uses an Individual Sector Protection method.

All of the listed flash memory products in this application note have the ability to protect individual 4KB and 64KB sectors and blocks of memory. Individual block protection is only effective after executing the WPSEL command. This one-time-use command permanently disables the block group protection method (Status Register BP bits) and activates individual block protection. The WPSEL command is common to both F and G versions.

## 4-2-1. Lock Register

Operating individual sector protection feature on F version and G version is similar. Both F and G version have SPB and DPB to implement individual sector protection feature.

To enhance the security of the protection feature, MX25L12845G/MX25L12873G provide SPB Lock Down feature, once SPBLKDN (Bit 6) is set, SPB bit value can not be changed again and it is read-only.

The Lock Register has slight difference. Please refer to the comparison table (*"Table 4-2: Lock register Comparison"*) and refer to MX25L12845G/MX25L12873G datasheets for more detailed information.

	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
bit 0	Reserved	RFU
bit 1	Solid Protection Mode Lock Bit	RFU
bit 2	Password Protection Mode Lock Bit	RFU
bit 3	Reserved	RFU
bit 4	Reserved	RFU
bit 5	Reserved	RFU
bit 6	Reserved	SPBLKDN
bit 7-15	Reserved	RFU

#### Table 4-2: Lock register Comparison





# 5. Register Comparison

The MX25L12835F/MX25L12873F and MX25L12845G/MX25L12873G Status Register bits are compatible.

Table 5-1: Status Register Compariso	on
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	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
bit 0	WIP (write in progress bit)	WIP (write in progress bit)
bit 1	WEL (write enable latch)	WEL (write enable latch)
bit 2	BP0 (level of protected block)	BP0 (level of protected block)
bit 3	BP1 (level of protected block)	BP1 (level of protected block)
bit 4	BP2 (level of protected block)	BP2 (level of protected block)
bit 5	BP3 (level of protected block)	BP3 (level of protected block)
bit 6	QE (Quad Enable)	QE (Quad Enable)
bit 7	SRWD (status register write protect)	SRWD (status register write protect)

The ODS setting has slight different between G and F version. G version adds Bit4 for Preamble bit Enable to improve data capture reliability while the flash memory is running in high frequency.

### Table 5-2: Configuration Register Comparison

	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G
bit 0	ODS 0 (output driver strength)	ODS 0 (output driver strength)
bit 1	ODS 1 (output driver strength)	ODS 1 (output driver strength)
bit 2	ODS 2 (output driver strength)	Reserved
bit 3	TB (top/bottom selected)	TB (top/bottom selected)
bit 4	Reserved	PBE (Preamble bit Enable)
bit 5	Reserved	Reserved
bit 6	DC0 (Dummy cycle 0)	DC0 (Dummy cycle 0)
bit 7	DC1 (Dummy cycle 1)	DC1 (Dummy cycle 1)





### Table 5-3: Security Register Comparison

	MX25L12835F MX25L12873F	MX25L12845G MX25L12873G	
bit 0	Secured OTP indicator bit	Secured OTP indicator bit	
bit 1	LDSO (indicate if lock-down)	LDSO (indicate if lock-down)	
bit 2	PSB (Program Suspend bit)	PSB (Program Suspend bit)	
bit 3	ESB (Erase Suspend bit)	ESB (Erase Suspend bit)	
bit 4	Reserved	Reserved	
bit 5	P_FAIL	P_FAIL E_FAIL WPSEL	
bit 6	E_FAIL		
bit 7	WPSEL		



# 6. Electrical Characteristics

The comparison of DC and AC characteristics are shown in Tables 6-1 and 6-2:

#### Table 6-1: DC Characteristics

DC Performance		MX25L12835F MX25L12873F	MX25L12845G MX25L12873G	
	Read (4I/O)	25mA @133MHz	25mA @133MHz	
Active Current		25111A @ 15510112	20mA @104MHz	
	Erase	25mA	25mA	
	Program	20mA	20mA	
VCC Standby Current		50uA	100uA	
Deep Power Down Current		20uA	20uA	

(Note: All of the data shown in Table 6-1 are maximum values).

#### Table 6-2: AC Characteristics

AC Performance		MX25L12835F MX25L12873F	MX25L12845G MX25L12873G	
	4КВ	typ	30ms	30ms
		max	120ms	400ms
	32КВ	typ	150ms	180ms
Erase Time		max	650ms	1000ms
	64КВ	typ	280ms	380ms
		max	650ms	2000ms
	Chip Erase	typ	50s	55s
		max	80s	100s
	Byte	typ	16us	15us
		max	300us	30us
Drogrom Timo	Page (256-Byte)	typ	0.5ms	0.25ms
Program Time		max	1.5ms	0.75ms
	Write Status Degister	typ	-	-
	Write Status Register	max	40ms	40ms
Erase/Program Cycles		typ	100,000	100,000
tCLQV (4I/O)	15pf	max	6ns	6ns
	30pf	max	8ns	8ns



# 7. Memory Organization

The memory and sector architecture of the MX25L12835F/MX25L12873F/MX25L12845G/MX25L12873G flash memory are identical.

# 8. Device Identification

The Manufacturer ID and Device ID values of the G version flash memory are identical to the F version flash memory.

ID item		MX25L12835F MX25L12873F	MX25L12845G MX25L12873G	
	Manufacturer ID	C2h	C2h	
RDID	Туре	20h	20h	
	Density	18h	18h	
RES	Electronic ID	17h	17h	
REMS	Manufacturer ID	C2h	C2h	
RENIS	Device ID	17h	17h	
	Manufacturer ID	C2h	C2h	
QPIID	Туре	20h	20h	
	Density	18h	18h	

### Table 8-1: Manufacturer ID & Device ID

## 9. Summary

Generally, the MX25L12835F/MX25L12873F/MX25L12845G/MX25L12873G are pin and command compatible with the basic Read/Program/Erase commands. There may be some differences if special features are used such as DTR mode, Advanced Sector Protection and Password protection.



# **10.Reference Documents**

Table 10-1 shows the datasheet versions used for comparison in this application note. For the most current Macronix specification, please refer to the Macronix Website at http://www.macronix.com

### Table 10-1: Datasheet Version

Datasheet	Location	Date Issued	Versions
MX25L12835F	Macronix Website	July 22, 2016	Rev. 1.6
MX25L12873F	Macronix Website	July 22, 2016	Rev. 1.2
MX25L12845G	Macronix Website	February 08, 2017	Rev 1.5
MX25L12873G	Macronix Website	September 02, 2016	Rev. 1.0

# **11. Revision History**

## Table 11-1: Revision History

Revision No.	Description	Page	Date
Rev. 1	Initial Release	ALL	February 13, 2017



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